

Poster ID	ID		Title
THU-P01	8		Advancing CMP R&D with Benchtop Systems: Cost-Effective Process Optimization and Consumable Characterization Damien Yiyuan Khoo* Bruker Nano Inc.
THU-P02	24	Student	Investigation of the Cleaning Mechanism in Amorphous Carbon Post-CMP cleaning Ziyang Wang, Pengzhan Liu, Hyeonjeon Lee, Hyunho Kim, Teasung Kim* Sungkyunkwan University
THU-P03	33		Enhanced Oxide Planarization for Advanced Packaging and Hybrid Bonding Simon Lee*, Minh-Che Ho Vibrantz Technologies
THU-P04	44		Hydrogen-Plasma Modification Model for GaN Surfaces Rongyan Sun*, Tong Tao, Yuji Ohkubo, Kazuya Yamamura The University of Osaka
THU-P05	59	Student	A High-Performance CeO₂ Slurry for Ultra-Precision Chemical Mechanical Polishing for Silicon Carbide Substrates Hui Jin, Xiuyan Sun, Taobao Jiang, Pan Liu* Fudan University
THU-P06	61		Synthesis of Mn-Doped Ceria Nanoparticles and Their Chemical Mechanical Polishing Performance on SiC Substrates Xiaogang Hu, Hong Lei* Shanghai University
THU-P07	63		New Smart Method for Sub 130 nm Slurry Particles Characterization-Size Measurement, Shape Recognition and Impact on CMP Process Performances Aurore Bonneville*, Silvio Del Monaco ST Microelectronics
THU-P08	69		Rheology and Tribology of Slurries—From Flow Curves to Stribeck Curves Kartik Pondicherry*, Paul Staudinger Anton Paar GmbH
THU-P09	72		CMP Slurry and Hydrogen Peroxide Concentration Monitoring Using Multiple Online Index of Refraction Sensors Takao Moriyasu, Tracy Gast*, Mark Bumiller Air Water Mechatronics Inc.
THU-P10	77	Student	Mechanistic Investigation of Inhibitor Mechanism in Mo CMP Ilhwa Hong, Donggeun Park, Dongwon Kim, Ganghyeok Kim, Kangchun Lee * Kwangwoon University
THU-P11	78	Student	pH-Tuned Approach for Defect Reduction During Poly Open CMP Donggeun Park, Ilhwa Hong, Dongwon Kim, Ganghyeok Kim, Kangchun Lee* Kwangwoon University
THU-P12	82		A Study on the Effect of Temperature on Polishing for Process Optimization Naoyuki Handa*, Yukihiko Kang, Shinnosuke Yamamoto, Shuntaro Hayashi, Ji Chul Yang, Itsuki Kobata, Nozomu Kuwabara, Selya Higuchi, Hiroharu Yukawa, Yasuyuki Motoshima, Shumpei Miura, Seunggho Yun, Toshiya Kon, Yumiko Nakamura, Takeshi Ohtsu, Akira Yamaguchi, Megumi Uno Ebara Corporation
THU-P13	85	Student	Effect of Nozzle Position on Liquid Film Thickness Distribution Formed by a Two-Fluid Jet Jukiya Ikegaya, Naoto Doi, Hiroki Takahashi, Masayoshi Imai, Toshiyuki Sanada* Shizuoka University
THU-P14	87	Student	Deformation and Behavior of Pva Brushes Induced by the Volume Change Makoto Miwa, Ryota Koshino, Toshiyuki Sanada* Shizuoka University
THU-P15	97		A Novel Wafer Contamination Standard with Micro-Scale Particle Positioning for Enhanced Defect Inspection Calibration Jiaqing Zhu*, Syuhei Kurokawa, Terutake Hayashi Huzhou University
THU-P16	108		Nano-Precision Metal Film Thickness Detection Technology by Using Eddy Current Principle Hongkai Li* Beijing Institute of Technology
THU-P17	109	Student	Study on the Enhancement of Silicon Carbide Removal Rate by Hybrid Abrasives in Chemical Mechanical Polishing Sihui Qin, Baoguo Zhang*, Wenhao Xian, Shitong Liu Hebei University of Technology
THU-P18	117		Computational Investigation of Multi-Coil Eddy Current Sensors with High Spatial Resolution for Chemical Mechanical Polishing Chengxin Wang*, Yikai Li, Zhiying Ren, Jianxiang Chen Fuzhou University
THU-P19	138		Effect of Brush Core Design on Liquid Flow During Scrub Cleaning Eri Okubo*, Nao Okuma, Yasushi Hongo, Toshimasa Mano, Toshiyuki Sanada AION Co., Ltd.
THU-P20	140		The Effect of Process Parameters and Cleaning Solution System on the Removal Behavior of Ceria Abrasives During Buff Cleaning Mei Yan, Lifei Zhang*, Dewen Zhao, Xinchun Lu Hwatsing Technology Co. Ltd.
THU-P21	141	Student	Stabilization of Polyvinyl Acetal (PVA) Brushes via Effective Removal of Intrinsic Impurities Through Advanced Cleaning Techniques Sanjay Bisht, Maheepal Yadav, Se-Hoon Park, Hirokuni Hiyaama, Tae-Gon Kim, Jin-Goo Park* Hanyang University
THU-P22	144	Student	Efficiency Enhancement in AlN CMP: Al₂O₃-Persulfate Synergy and Mechanisms Shitong Liu, Baoguo Zhang*, Wenhao Xian, Sihui qin, Yaqing Li Hebei University of Technology
THU-P23	149	Student	Effect of Pad Temperature on Within-Wafer Uniformity in CMP Daehoon Kang, Taesung Kim* Sungkyunkwan University
THU-P24	151	student	Fine Slurry Residue Removal in Hard-Pad CMP by Tuning Process Conditions Hyunjin Jeong, Minju Lee, and Taesung Kim*
THU-P25	161		Emerging Stress-Free Ruthenium Removal Study in Advanced Node Interconnect Structure Yinuo Jin*, Jian Wang, Junzhong Zhang, Pengfei Chang, Rong Yu, Chen Wang ACM Research (Shanghai), Inc.
THU-P26	162	Student	Microfabrication of Miniaturized Eddy Current Sensors and Inductance Enhancement via Origami Stacking Dong Geun Kim, Kyunghyun Kim, Seong Jae Kim, Sanha Kim* KAIST
THU-P27	165	Student	Effect of Synthesis Materials and Process Parameters on Polyvinyl Acetal (PVA) Brushes Properties and Incoming Impurities Maheepal Yadav, Sanjay Bisht, Se-Hoon Park, Tae-Gon Kim, Hirokuni Hiyaama, Jin-Goo Park* Hanyang University
THU-P28	166		Development of Low-Defect Solutions for Next-Generation Polysilicon CMP Process Through Synergistic Integration of Slurry and Post-CMP Cleaning Chemistries Kuan Ting Lin* Formation Scientist
THU-P29	178		Post-CMP Buffing Cleaner with Excellent Particle Cleaning via Effective Wafer Surface Passivation Ying-Pei Huang*, Chih-Wei Lin, Syuan-Fu Chen, Chia-Te Chang, Yi-Ling Chang, Wei-En Hsu, Hong-Yi Chiang, Li-Yu Chen, Wei-En Huang, Ping Hsu Qnity™, DuPont Electronics
THU-P30	183	Student	Study the Effect of Dicarboxylic Acid Stabilizers and Amino Acid Corrosion Inhibitors on Tungsten Chemical Mechanical Planarization Performance Changhao Zheng, Weili Liu* Shanghai Institute of Microsystem and Information Technology, Chinese Academy of Sciences
THU-P31	185		Investigation of Metal Compatibility of Acidic Post CMP Cleaner Designed for Ceria Abrasives Kohei Endo, Hiroaki Iwamoto*, Kenta Natsukawa, Shota Yoshioka AGC Inc.

THU-P32	190	Student	Effect of Chelating Agents and Stabilizers on the Material Removal Rate and Surface Quality in Magnesium Aluminate Spinel Chemical Mechanical Polishing Yaowen Li, Weili Liu*, Zhitang Song Shanghai Institute of Microsystem and Information Technology, Chinese Academy of Sciences
THU-P33	192		CMP Slurry Filtration Using Innovative Membrane Technology Majid Entezarian*, John Morby, Sandeep Singh, Pierre Alexandre Bourgeois Solventum
THU-P34	193		In-Line Real-Time Measurement of Recycled CMP Slurry Using Ultrasound Raymond Maas* Rhosonics
THU-P35	195		Revolutionizing Post-CMP Cleaner Development: A Machine Learning Approach Abby Tsai, Jacky Cheng, Grace Liu, Michelle Sun, Ping Hsu, Peter Sun* Qnity™, DuPont Electronics
THU-P36	200	Student	High-Efficiency Post-CMP Cleaning of Ceria Nanoparticles on SiO₂ with CO₂ Nanobubble Water Xuhao Cao, Nan Guan, Boao Ma, Yuze Liu, Linyi Shen, Chunfeng Hu, Lijuan Zhang, XinPing Qu* Fudan University
THU-P37	208		From Lab to Fab: The Art and Science of Capturing the Uncatchable in CMP Filtration YuChieh Fu* Entegris
THU-P38	209		New Development of Fine Particle Count (FPC) Reduction Yu heng Cheng* Entegris
THU-P39	212	Student	Research on Surface Quality Enhancement of Zinc Oxide Thin Films in CMP Yaqing Li* Hebei University of Technology